



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-09-07
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Floriana SAN BIAGIO	Representative Title	AMS MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	KD6P*1872ARY	A	BO2A	2018-09-07
	Amount	UoM	Unit type	ST ECOPACK Grade
	34.89	mg	Each	ECOPACK® 3
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.4x3x0.9	8	gull wing	
Comment	6P TSSOP 8 BODY 4.4 PITCH 0.65; MDF valid for TSV358AIYPT			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
;				
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	KDG#1872ARY				4999999.0	1000029.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	1.498	mg	supplier	die	Silicon (Si)	7440-21-3		1.486	mg	991989	42591
				supplier	metallization	Aluminium (Al)	7429-90-5		0.005	mg	3338	143
				supplier	Passivation	Silicon Nitride	12033-89-5		0.004	mg	2670	115
				supplier	Passivation	Silicon Oxide	7631-86-9		0.003	mg	2003	86
				supplier	alloy	Copper (Cu)	7440-50-8		13.991	mg	943171	401003
				supplier	alloy	Nickel (Ni)	7440-02-0		0.436	mg	29392	12496
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.022	mg	1483	631
				supplier	alloy	Silicon (Si)	7440-21-3		0.095	mg	6404	2723
				supplier	metallization	Nickel (Ni)	7440-02-0		0.266	mg	17932	7624
	M-006 Nickel and its alloys			supplier	metallization	Palladium (Pd)	7440-05-3		0.017	mg	1146	487
	M-008 Precious metals			supplier	metallization	Gold (Au)	7440-57-5		0.007	mg	472	201
	M-008 Precious metals			supplier	metallization	Silver (Ag)	7440-22-4		0.501	mg	875874	14359
Die attach	M-015 Other organic materials	0.572	mg	supplier	glue	Isobornyl Methacrylate	7534-94-3		0.029	mg	50699	831
				supplier	glue	Acrylate resin	5888-33-5		0.029	mg	50699	831
				supplier	glue	Methyl acrylate polymer	87320-05-6		0.011	mg	19231	315
				supplier	glue	Epoxy cyclohexylethyltrimethoxysilane	3388-04-3		0.001	mg	1748	29
				supplier	glue	Tert-Butyl peroxy(2-ethyl)-hexanoate	3006-82-4		0.001	mg	1748	29
				supplier	wire	Copper (Cu)	7440-50-8		0.036	mg	1000000	1032
Encapsulation	M-015 Other organic materials	17.951	mg	supplier	mold compound	Silica, vitreous	60676-86-0		15.742	mg	876943	451189
				supplier	mold compound	Epoxy resin	85954-11-6		0.718	mg	39998	20579
				supplier	mold compound	Epoxy	29690-82-2		0.718	mg	39998	20579
				supplier	mold compound	phenol resin	Proprietary		0.539	mg	30026	15449
				supplier	mold compound	additive	Proprietary		0.180	mg	10027	5159
				supplier	mold compound	carbon black	1333-86-4		0.054	mg	3008	1548